ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® Material Comp © Copyright 2005. I international and Pa	PC Bannockl	burn Illinois. A	ll rights reserved nations.	under both	This docume level parts, t	ent is a declarati he declaration e	on of the su	ibstances s all lower	within the manufactor r level materials for v	urer listed which the	item. Note: manufactur	: if the item is an as er has engineering	sembly with lower responsibility.	
T52 21 1 IPC Web Site for Information on IPC-1752 Standard F			Form Type Distribute					rials and N	ials and Mfg Information					
Supplier Information														
Company name* Co			Company unique ID			Unique ID Authority				Respon	Response Date*			
onsemi											2025-08-31			
Contact Name Title - Contact				Phone - Contact*				Email - Contact*						
Product-Env-Stewards Product			oduct Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title -			itle - Representative			Phone - Representative*				Email	Email - Representative*			
Product-Env-Stewards	Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Iten	n Number	ber Mfr Item Name			Effective Date	Version	ersion Manufacturing Site			Weight*	UOM	Unit Type	
	NSBC12	SBC124EPDP6T5G SOT-963 COMP NE		NBRT		2025-08-31					1.19	mg	Each	
Manufacturing Proccess Informa	tion						-	·						
Terminal Plating / Grid Array M	aterial	al Terminal Base Alloy		J-STD-020 MS	L Rating	Peak Proc	Process Body Temperature Max Time at Pea		k Tempera	ture Nun	nber of Reflow Cyc	eles		
Matte Tin (Sn) - annealed CU A		CU Alloy	1			260 C		С	30 seco		seconds 3			
Comments														
evel 1 - maximum time at peak temperat	ure during so	ldering is 10-3	0 seconds											
for more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless	otherwise noted).							
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.03	mg	Supplier	Silicon (Si)	7440-21-3		0.03	mg
Lead Frame	0.52	mg	Supplier	Silver (Ag)	7440-22-4		0.0473	mg
			В	Nickel (Ni)	7440-02-0		0.1914	mg
			Supplier	Iron (Fe)	7439-89-6		0.2626	mg
			Supplier	Copper (Cu)	7440-50-8		0.0187	mg
Mold Compound-Black	0.61	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.061	mg
			Supplier	Carbon Black (C)	1333-86-4		0.003	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.0884	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.3965	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.061	mg
Plating	0.02	mg	Supplier	Tin (Sn)	7440-31-5		0.02	mg
Wire Bond - Cu	0.01	mg	Supplier	Copper (Cu)	7440-50-8		0.01	mg